

## ABSTRACT OF THE DISCLOSURE

A contact structure (10) and a process for producing a contact structure are provided for connecting two substrates (11, 12). The process includes applying solder material (23) to terminal areas (16) of a first substrate (11) to form spacing metallizations (19), and bonding of the first substrate (11) with a second substrate (12). The bonding between the terminal areas (16) of the first substrate (11) and a contact surface area of the second substrate (12) is performed by means of an electrically conductive adhesive compound (20).